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# **Biomaterials, Biodevices and Tissue Engineering, Second Edition**

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### **Message from the Guest Editors**

# Dear Colleagues,

The innovation in biomaterials in several forms. compositions, and uses has seen exponential growth over the past 10 years and has led to increased confidence in the industry as regards the design and fabrication of biomedical devices that can be used as drug delivery systems, in tissue engineering, and as bioelectronic devices such as biosensors or organic solar cells. Additionally, the construction of nanostructures has led to many advantageous characteristics of these biomaterials, stimulating their bioactivity due to the accessibility of many tissues or incrementing the surface area, leading to a higher load of a bioactive component, among others. Accordingly, this Special Issue seeks to showcase research papers, communications, and review articles that focus on novel methodological developments in micro- and nanoscale fabrication, novel synthesis processes, chemical compositions, nanostructures, coatings, or bioactivity and tissue response in areas of application of tissue engineering, drug delivery systems, and biomedical devices

We look forward to receiving your submissions.

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### Message from the Editor-in-Chief

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